

April 2000

FQA7N60

600V N-Channel MOSFET

General Description

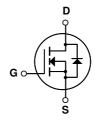
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supply.

Features

- 7.7A, 600V, $R_{DS(on)} = 1.0\Omega$ @V_{GS} = 10 V Low gate charge (typical 29 nC)
- Low Crss (typical 16 pF)
- · Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings $T_C = 25$ °C unless otherwise noted

Symbol	Parameter		FQA7N60	Units	
V _{DSS}	Drain-Source Voltage		600	V	
I _D	Drain Current - Continuous (T _C = 25°	C)	7.7	Α	
	- Continuous (T _C = 100	°C)	4.8	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	30.8	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	580	mJ	
I _{AR}	Avalanche Current	(Note 1)	7.7	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	15.2	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns	
P _D	Power Dissipation (T _C = 25°C) - Derate above 25°C		152	W	
			1.22	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
TL	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.82	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced	to 25°C		0.67		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600 V, V _{GS} = 0 V				10	μΑ
		V _{DS} = 480 V, T _C = 125°C	V _{DS} = 480 V, T _C = 125°C		-	100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$			-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 3.9 \text{ A}$			0.8	1.0	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 3.9 A	(Note 4)		6.5		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz			1100 135 16	175 21	pF pF
	-				16	21	p⊦
	ing Characteristics	I				70	
t _{d(on)}	Turn-On Delay Time	V_{DD} = 300 V, I_{D} = 7.4 A, R_{G} = 25 Ω (Note 4, 5			30	70	ns
t _r	Turn-On Rise Time				80	170	ns
t _{d(off)}	Turn-Off Delay Time				65	140	ns
t _f	Turn-Off Fall Time		(, -,		60	130	ns
Q _g	Total Gate Charge	$V_{DS} = 480 \text{ V}, I_{D} = 7.4 \text{ A},$			29	38	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V (Note 4, 5			7 14.5		nC nC
Q _{gd}	Gate-Drain Charge		(11010 1, 0)		14.5		ПС
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings	S				
I _S	Maximum Continuous Drain-Source Diode Forward Current					7.7	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	ource Diode Forward Current				30.8	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 7.7 \text{ A}$				1.4	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 7.4 \text{ A},$			320		ns
**	,	40 . 0	(Note 4)				

Notes:1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 18mH, I_{AS} = 7.7A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C 3. I_{SD} ≤ 7.4A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% 5. Essentially independent of operating temperature

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Typical Characteristics

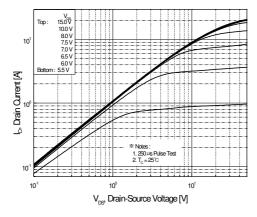


Figure 1. On-Region Characteristics

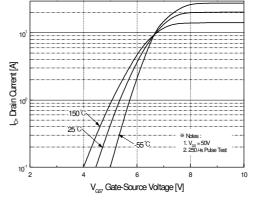


Figure 2. Transfer Characteristics

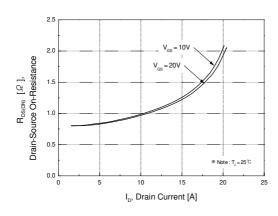


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

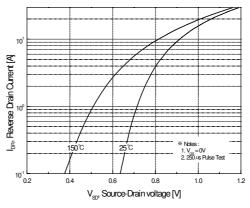


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

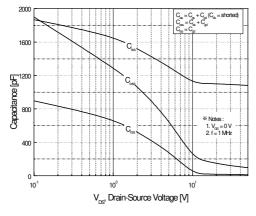


Figure 5. Capacitance Characteristics

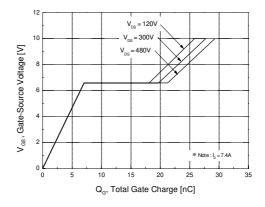


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

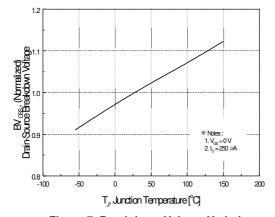


Figure 7. Breakdown Voltage Variation vs. Temperature

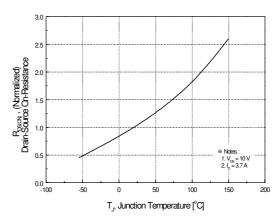


Figure 8. On-Resistance Variation vs. Temperature

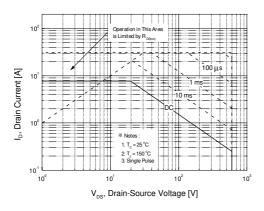


Figure 9. Maximum Safe Operating Area

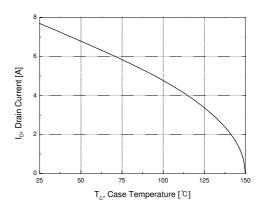


Figure 10. Maximum Drain Current vs. Case Temperature

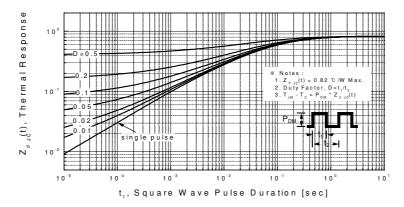
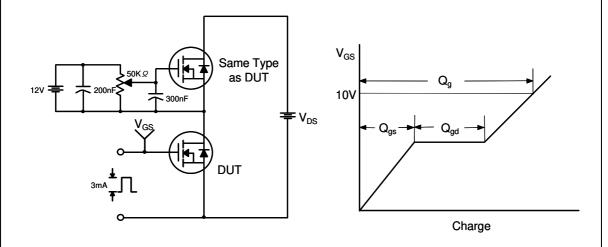


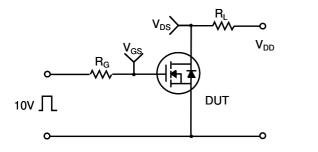
Figure 11. Transient Thermal Response Curve

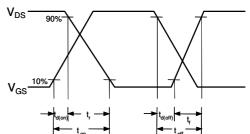
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Gate Charge Test Circuit & Waveform

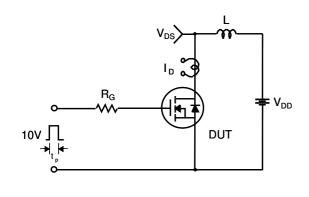


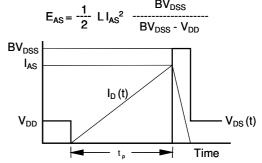
Resistive Switching Test Circuit & Waveforms



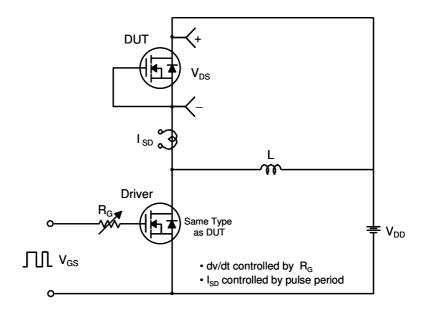


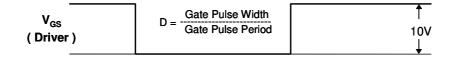
Unclamped Inductive Switching Test Circuit & Waveforms

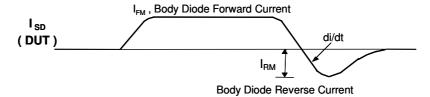


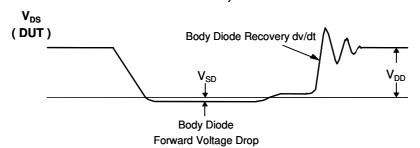


Peak Diode Recovery dv/dt Test Circuit & Waveforms

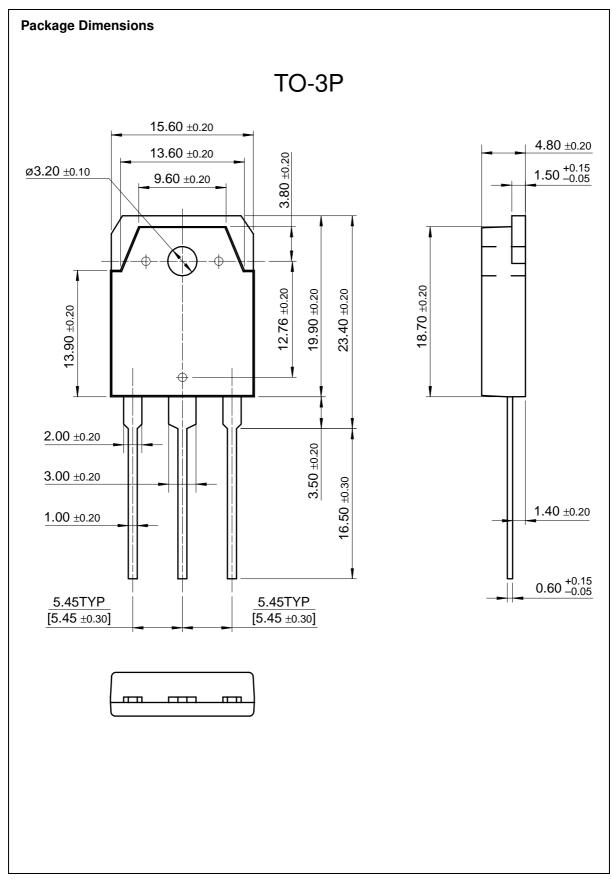








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